

BICMOS INTEGRATED CIRCUIT $\mu PC1933$

DC-DC CONVERTER CONTROL IC

DESCRIPTION

The μ PC1933 is an IC that controls a low-voltage input DC-DC converter. This IC is suitable for an operation with 3-V, 3.3-V input or a lithium ion secondary battery input, because the minimum operating supply voltage is 2.5 V.

Because of its wide operating voltage range, it can also be used to control DC-DC converters that use an AC adapter for input.

FEATURES

- Low supply voltage: 2.5 V (MIN.)
- Operating voltage range: 2.5 to 20 V (breakdown voltage: 30 V)
- Timer latch circuit for short-circuit protection.
- Ceramic capacitor with low capacitance (0.1 μ F) can be used for short-circuit protection.
- Open drain output (1 cannel: This output can be used to control a step-down converter, a step-up converter.)
- Dead time is internally fixed to 85 %.
- Soft start function (with a circuit to convert the timer latch circuit.)

ORDERING INFORMATION

Part Number	Package	
μ PC1933GR	8-pin plastic SOP (5.72 mm (225))	

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BLOCK DIAGRAM



PIN CONFIGURATION (Top View)

8-pin plastic SOP (5.72 mm (225))

• µ PC1933GR



PIN FUNCTIONS

Pin No.	Symbol	Function	Pin No.	Symbol	Function
1	h	Error amplifier inverted input	5	OUT	Open-drain output
2	DLY	Short-circuit protection	6	GND	Ground
3	Vcc	Power supply	7	R⊤	Frequency setting resistor connection
4	Vref	Reference voltage output	8	FB	Error amplifier output

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1. ELECTRICAL SPECIFICATIONS

Absolute Maximum Ratings (unless otherwise specified, T_A = 25 °C)

Parameter	Symbol	Ratings	Unit
Supply voltage	Vcc	30	V
Output voltage	Vo	30	V
Output current (open drain output)	lo	21	mA
Total power dissipation	Ρτ	480	mW
Operating ambient temperature	TA	-20 to + 85	°C
Storage temperature	Tstg	-55 to + 150	°C

Caution Product quality may suffer if the absolute maximum rating is exceeded even momentarily for any parameter. That is, the absolute maximum ratings are rated values at which the product is on the verge of suffering physical damage, and therefore the product must be used under conditions that ensure that the absolute maximum ratings are not exceeded.

Recommended Operating Conditions

Parameter	Symbol		Ratings		Unit
Supply voltage	Vcc	2.5		20	V
Output voltage	Vo	0		20	V
Output current	lo			20	mA
Operating temperature	TA	-20		+85	°C
Oscillation frequency	fosc	20		800	kHz

★ Caution The recommended operating range may be exceeded without causing any problems provided that the absolute maximum ratings are not exceeded. However, if the device is operated in a way that exceeds the recommended operating conditions, the margin between the actual conditions of use and the absolute maximum ratings is small, and therefore thorough evaluation is necessary. The recommended operating conditions do not imply that the device can be used with all values at their maximum values.

	Block	Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
ſ	Under	Start-up voltage	Vcc (L-H)	IREF = 0.1 mA		1.57		V
	voltage	Operation stop voltage	Vcc (H-L)	IREF = 0.1 mA		1.5		V
	Lock-out	Hysteresis voltage	Vн	IREF = 0.1 mA	30	70		mV
	section	Reset voltage (timer latch)	VCCR	IREF = 0.1 mA		1.0		V
	Reference	Reference voltage	Vref	Iref = 1 mA	2.0	2.1	2.2	V
*	Voltage	Line regulation	REGIN	2.5 V≤Vcc≤20 V		2	12.5	mV
*	section	Load regulation	REG∟	0.1 mA≤Iref≤1 mA		2	7.5	mV
		Temperature coefficient	$\Delta V_{REF} / \Delta T$	-20 °C≤Ta≤+85 °C, Iref = 0 A		0.5		%
	Oscillation	fosc setting accuracy	Δfosc	Rτ = 18 kΩ	-20		+30	%
	section	fosc total stability	∆fosc	–20 °C≤Ta≤+85 °C,	-20		+50	%
				2.5 V≤Vcc≤20 V				
	PWM	Maximum duty	Dmax.			85		%
	comparator section	Soft start time	tss	$C_{DLY} = 0.1 \mu F$		50		ms
	Error	Input threshold voltage	VITH		0.285	0.3	0.315	V
	Amplifier	Input bias current	Ів		-100		+100	nA
	section	Open loop gain	Av	Vo = 0.3 V	70	80		dB
		Unity gain	funity	Vo = 0.3 V		1.5		MHz
		Maximum output voltage (+)	Vom ⁺	lo = -45 μA	1.6	2		V
*		Maximum output voltage (-)	Vom ⁻	lo = 45 μA		0.02	0.5	V
		Output sink current	lOsink	Vfb = 0.5 V	0.8	1.4		mA
		Output source current	Osource	Vfb = 1.6 V		-70	-45	μA
	Output	Drain cutoff current	ILEAK	Vo = 30 V			100	μA
*	section	Output ON voltage	Vol	R _L = 150 Ω		0.2	0.6	V
		Rise time	tr	R _L = 150 Ω		50		ns
		Fall time	tr	R _L = 150 Ω		60		ns
*	Short-circuit	Input sense voltage	Vтн		1.75	1.92	2.05	V
*	Protection	UV sense voltage	Vuv			0.8	0.85	V
*	section	Source current on short-circuiting	Ιουν		1.0	1.6	2.7	μA
		Delay time	t dly	$C_{DLY} = 0.1 \mu F$		50		ms
*	Overall	Circuit operation current	lcc	Vcc = 3 V	1.4	2.6	3.9	mA

Caution Connect a capacitor of 0.01 to 10 μ F to the VREF pin.



Timing Chart



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Typical Characteristic Curves (unless otherwise specified, Vcc = 3 V, fosc = 100 kHz, TA = 25 °C) (Nominal)

100

0.4

1.0

180

135

90

45

0

-45

-90

10 M

1 M

Phase ϕ (deg)



75

100



★ 2. CONFIGURATION AND OPERATION OF EACH BLOCK



Figure 2-1 Block Diagram

2.1 Reference Voltage Generator

The reference voltage generator is comprised of a band-gap reference circuit, and outputs a temperature-compensated reference voltage (2.1 V). The reference voltage can be used as the power supply for internal circuits, or as a reference voltage, and can also be accessed externally via the VREF pin (pin 4).

2.2 Oscillator

The oscillator self-oscillates if a timing resistor is attached to the R_T pin (pin 7). This oscillator waveform is input to the inverted input pin of the PWM comparator to determine the oscillation frequency.

2.3 Under Voltage Lock-out Circuit

The under voltage lock-out circuit prevents malfunctioning of the internal circuits when the supply voltage is low, such as when the supply voltage is first applied, or when the power supply is interrupted. When the voltage is low, the output transistor is cut off at the same time.

2.4 Error Amplifier

The non-inverted input pin of the error amplifier is connected internally to 0.3 V (the input threshold voltage is 0.3 V (TYP.)). The first stage of the error amplifier is a P-channel MOS transistor input.

2.5 PWM Comparator

The output ON duty is controlled according to the outputs of the error amplifier.

A triangular waveform is input to the inverted pin, and the error amplifier output and Dead Time Control pin voltage (fixed internally) are input to the non-inverted pins of the PWM comparator. Therefore, the output transistor ON period is the period when the triangular waveform is lower than the error amplifier output and Dead Time Control pin voltage (fixed internally) (refer to **Timing Chart**).

2.6 Timer Latch-Method Short Circuit Protection Circuit

When the output of the converter drops, the non-inverted input pin (1 pin) voltage of the error amplifier drops, and the FB output of the error amplifier of the output goes high. If the FB output exceeds the timer latch input detection voltage ($V_{TH} = 1.92 \text{ V}$), then the output of the SCP comparator goes low, and Q₁ goes off.

When Q₁ turns OFF, the constant-current supply charges C_{DLY} via the DLY pin. The DLY pin is internally connected to a flip-flop. When the DLY pin voltage reaches the UV detection voltage (Vuv = 0.7 V (TYP.)), the output Q of the flip-flop goes low, and the output stage is latched to OFF (refer to **Figure 2-1 Block Diagram**).

Make the power supply voltage briefly less than the reset voltage (VCCR, 1.0 V TYP.) to reset the latch circuit when the short-circuit protection circuit has operated.

2.7 Output Circuit

The output circuit has an N-channel open-drain output providing an output withstand voltage of 30 V (absolute maximum rating), and an output current of 21 mA (absolute maximum rating).

★ 3. NOTES ON USE

3.1 Setting the Output Voltage

Figure 3-1 illustrates the method of setting the output voltage. The output voltage is obtained using the formula shown in the figure.

The input threshold value of the error amplifier is 0.3 V (TYP.) for the error amplifier. Therefore, select a resistor value that gives this voltage.





3.2 Setting the Oscillation Frequency

Choose R_T according to the oscillation frequency (fosc) vs timing resistor (R_T) characteristics (refer to **Typical Characteristics Curves fosc vs R**T.) The formula below (3-1) gives an approximation of fosc. However, the result of formula 3-1 is only an approximation, and the value must be confirmed in actual operation, especially for high-frequency operation.

fosc[Hz]
$$\cong$$
 1.856 x 10⁹/R_T[Ω] (3-1)

3.3 Preventing Malfunction of the Timer Latch-Method Short Circuit Protection Circuit

The timer latch short-circuit protection circuit operates when the error amplifier output (pin 8) exceed approximately 1.92 V, and cuts off the output. However, if the rise of the power supply voltage is fast, or if there is noise on the DLY pin (pin 2), the latch circuit may malfunction and cut the output off.

To prevent this, lower the wiring impedance between the DLY pin and the GND pin (pin 6), and avoid applying noise to the DLY pin.

3.4 ON/OFF Control

The ON/OFF control method of the output oscillation is to input the ON/OFF signal from ON as shown in Figure 3-2. Soft start or timer latch (SCP) is internally selected. Soft start is executed when the first start signal is input. When the end of soft start is detected, the soft start select switch is turned OFF and the timer latch circuit operates.



Figure 3-2 ON/OFF Control

(1) When ON is high: OFF status

 $Q_1 {:}\ ON \rightarrow DLY$ pin: Low level \rightarrow Output duty of PWM comparator: 0 %

 $D_1 : ON \rightarrow I_1 \text{ pin: High level} \rightarrow FB$ output: Low level

(2) When ON is low: ON status (start up)

 $Q_1: OFF \rightarrow C_{\text{DLY}} \text{ is charged in the sequence of } [V_{\text{REF}} \rightarrow R_1 \rightarrow SW \rightarrow DLY \text{ pin} \rightarrow C_{\text{DLY}}] \rightarrow Soft \text{ start}$

 $D_1: OFF \rightarrow I_1$ pin: Low level \rightarrow FB output: High level

(3) When ON goes high again after start up (SW: OFF): OFF status

 $Q_1: ON \rightarrow DLY$ pin: Low level (Nothing happens because SW is OFF.)

D1: ON \rightarrow I pin: High level \rightarrow FB output: Low level \rightarrow PWM comparator output duty: 0 %

 \rightarrow Converter output voltage (Vo) drops.

Caution Even if start up is executed by making ON low again after (3), soft start is not executed because the soft start select switch (SW) remains OFF. To execute soft start again, drop Vcc to 0 V once.

3.5 Maximum Duty Limit

 μ PC1933 is switched internally between Soft Start and Timer Latch. For this reason, the DTC voltage is fixed internally, and the maximum duty is limited to 85%.

3.6 Notes on Actual Pattern Wiring

When actually carrying out the pattern wiring, it is necessary to separate control-related grounds and power-related grounds, and make sure that they do not share impedances as far as possible. In addition, make sure the high-frequency impedance is lowered using capacitors and other components to prevent noise input to the VREF pin.

★ 4. APPLICATION EXAMPLE

4.1 Application Example

Figure 4-1 shows an example circuit for obtaining +5 V/50 mA from a +3 V power supply.

Figure 4-1 Application Example



4.2 List of External Parts

The list below shows the external parts.

Table 4-1 List of Extern	nal Parts
--------------------------	-----------

Symbol	Parameter	Function	Part number	Maker	Remark
C ₄	68 <i>µ</i> F	Output capacitor	20SA68M	SANYO	OS-CON, SA series
D1		Schottkey diode	D1FS4	SHINDENGEN	
L1	47 μ H	Choke inductor	636FY-470M	токо	D73F series
Q ₃		Switching transistor	2SD2403	NEC	
Q1		Buffer transistor	2SC1623	NEC	
Q2		Buffer transistor	2SA812	NEC	

Remarks 1. The capacitors that are not specified in the above list are multilayer ceramic capacitors.

2. The resistors that are not specified in the above list are 1/4W resistors.

5. PACKAGE DRAWING

8-PIN PLASTIC SOP (5.72 mm (225))



detail of lead end







ΝΟΤΕ

Each lead centerline is located within 0.12 mm of its true position (T.P.) at maximum material condition.

ITEM	MILLIMETERS
А	$5.2 \begin{array}{c} +0.17 \\ -0.20 \end{array}$
В	0.78 MAX.
С	1.27 (T.P.)
D	$0.42\substack{+0.08\\-0.07}$
E	0.1±0.1
F	1.59±0.21
G	1.49
Н	6.5±0.3
I	4.4±0.15
J	1.1±0.2
к	$0.17\substack{+0.08\\-0.07}$
L	0.6±0.2
М	0.12
Ν	0.10
Р	3° ^{+7°} 3°
	S8GM-50-225B-6

6. RECOMMENDED SOLDERING CONDITIONS

Recommended solder conditions for this product are described below.

For details on recommended soldering conditions, refer to Information Document "Semiconductor Device Mounting

Technology Manual" (C10535E).

For soldering methods and conditions other than those recommended, consult NEC.

Surface Mount Type

μ PC1933GR: 8-pin plastic SOP (5.72 mm (225))

Soldering Method	Soldering Conditions	Symbol of Recommended Conditions
Infrared reflow	Package peak temperature: 235 °C, Time: 30 seconds MAX. (210 °C MIN.), Number of times: 3 MAX.	IR35-00-3
VPS	Package peak temperature: 215 °C, Time: 40 seconds MAX. (200 °C MIN.), Number of times: 3 MAX.	VP15-00-3
Wave soldering	Soldering bath temperature: 260 °C MAX., Time: 10 seconds MAX., Number of times: 1, Preheating temperature: 120 °C MAX. (package surface temperature)	WS60-00-1

Caution Do not use two or more soldering methods in combination.

NOTES FOR BICMOS DEVICES

1 PRECAUTION AGAINST ESD FOR SEMICONDUCTORS

Note:

Strong electric field, when exposed to a device, can cause destruction of the gate oxide and ultimately degrade the device operation. Steps must be taken to stop generation of static electricity as much as possible, and quickly dissipate it once, when it has occurred. Environmental control must be adequate. When it is dry, humidifier should be used. It is recommended to avoid using insulators that easily build static electricity. Semiconductor devices must be stored and transported in an anti-static container, static shielding bag or conductive material. All test and measurement tools including work bench and floor should be grounded. The operator should be grounded using wrist strap. Semiconductor devices must not be touched with bare hands. Similar precautions need to be taken for PW boards with semiconductor devices on it.

(2) HANDLING OF UNUSED INPUT PINS

Note:

No connection for device inputs can be cause of malfunction. If no connection is provided to the input pins, it is possible that an internal input level may be generated due to noise, etc., hence causing malfunction. Input levels of devices must be fixed high or low by using a pull-up or pull-down circuitry. Each unused pin should be connected to VDD or GND with a resistor, if it is considered to have a possibility of being an output pin. All handling related to the unused pins must be judged device by device and related specifications governing the devices.

③ STATUS BEFORE INITIALIZATION OF BICMOS DEVICES

Note:

Power-on does not necessarily define initial status of device. Production process of BiCMOS does not define the initial operation status of the device. Immediately after the power source is turned ON, the devices with reset function have not yet been initialized. Hence, power-on does not guarantee out-pin levels, I/O settings or contents of registers. Device is not initialized until the reset signal is received. Reset operation must be executed immediately after power-on for devices having reset function.

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 before using it in a particular application.
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 - Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
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